



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

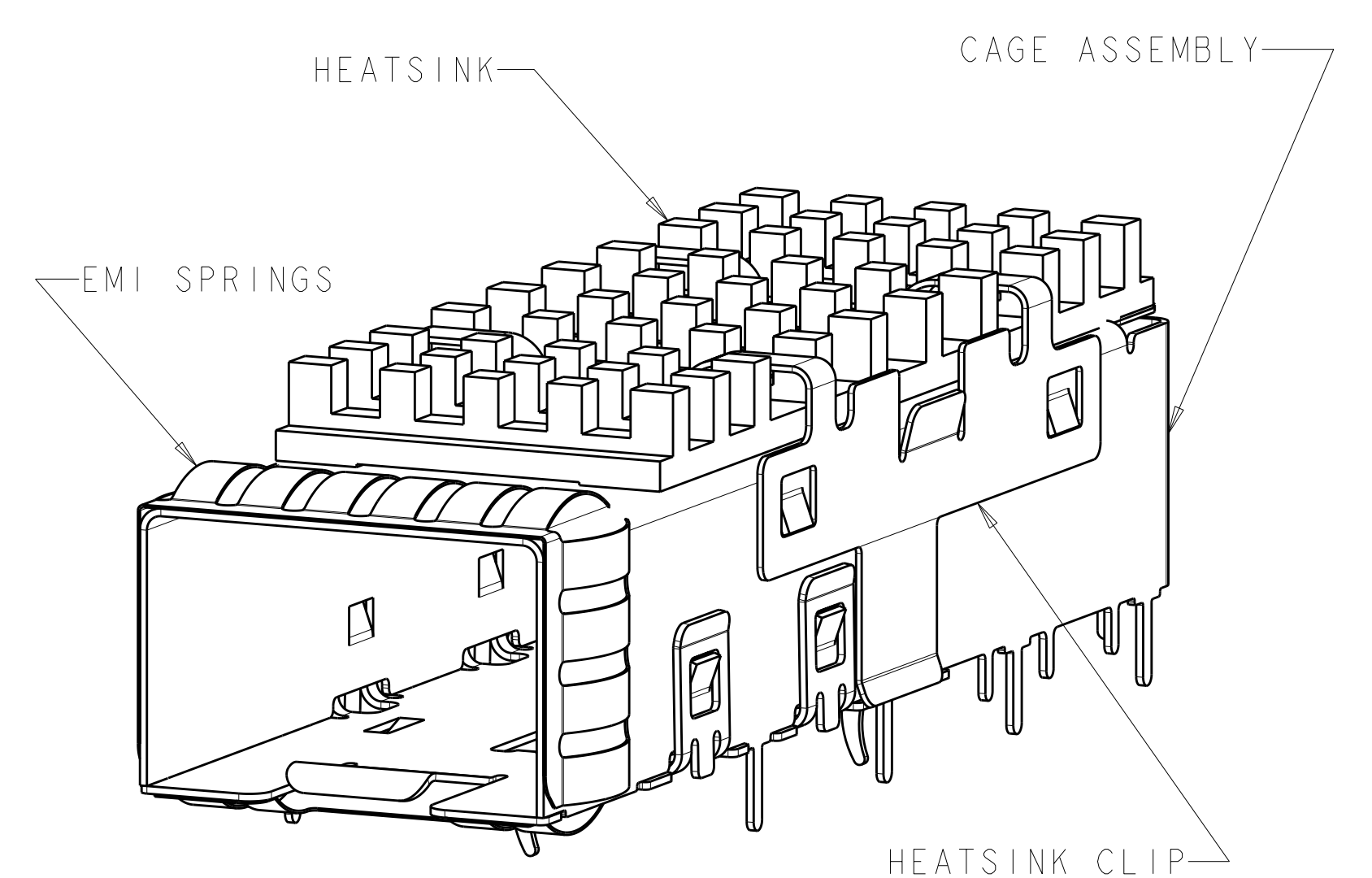
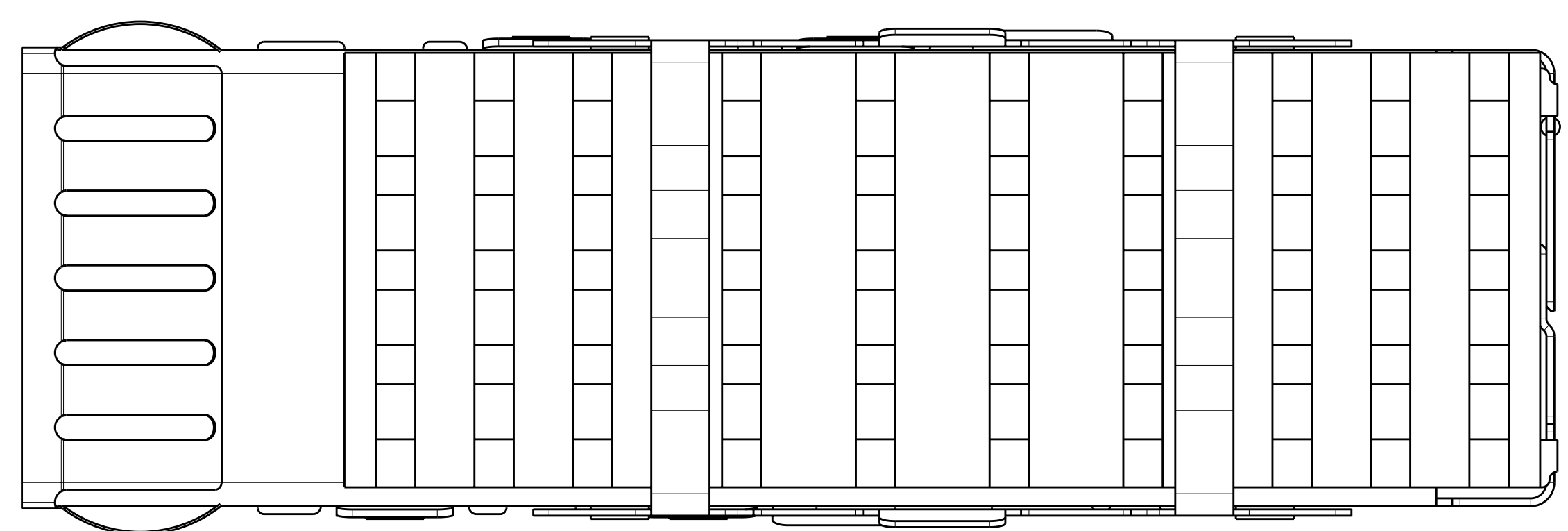
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

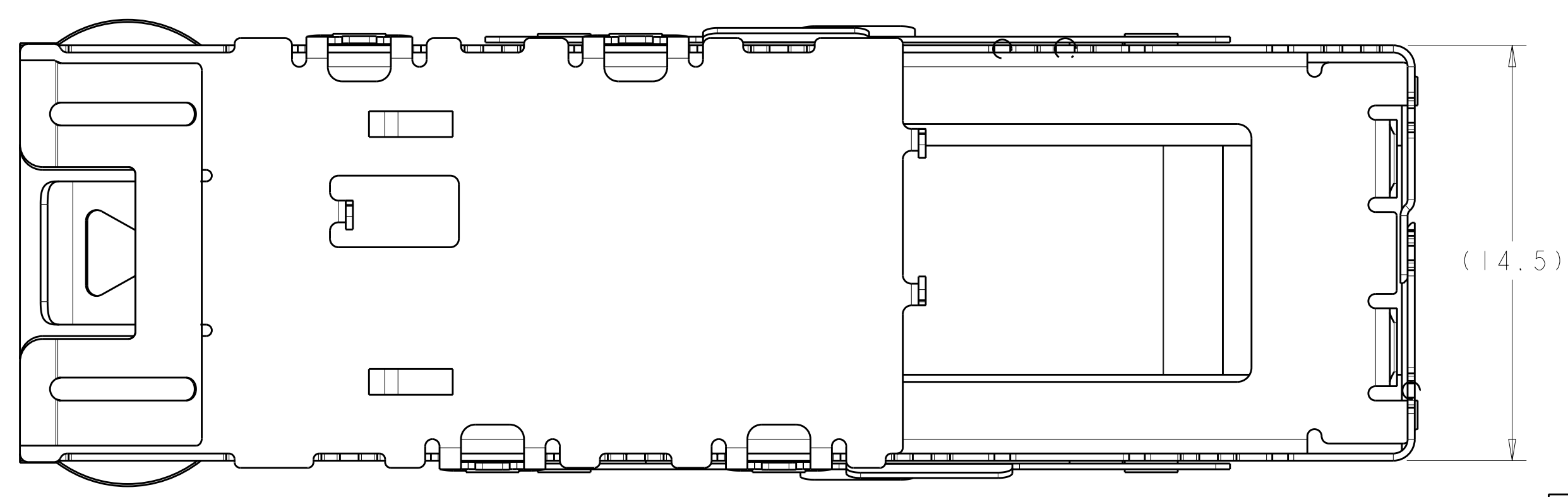
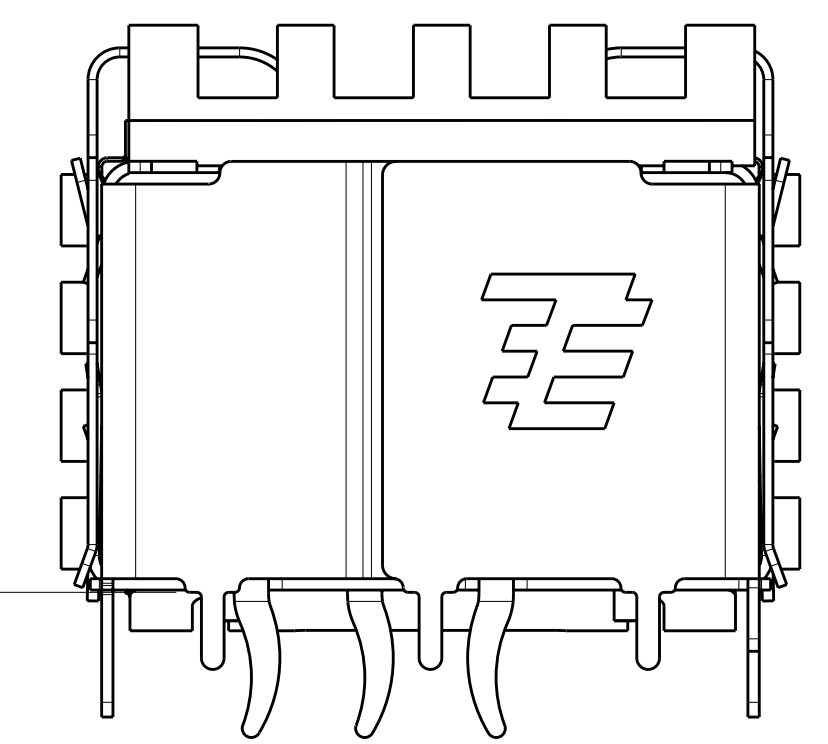
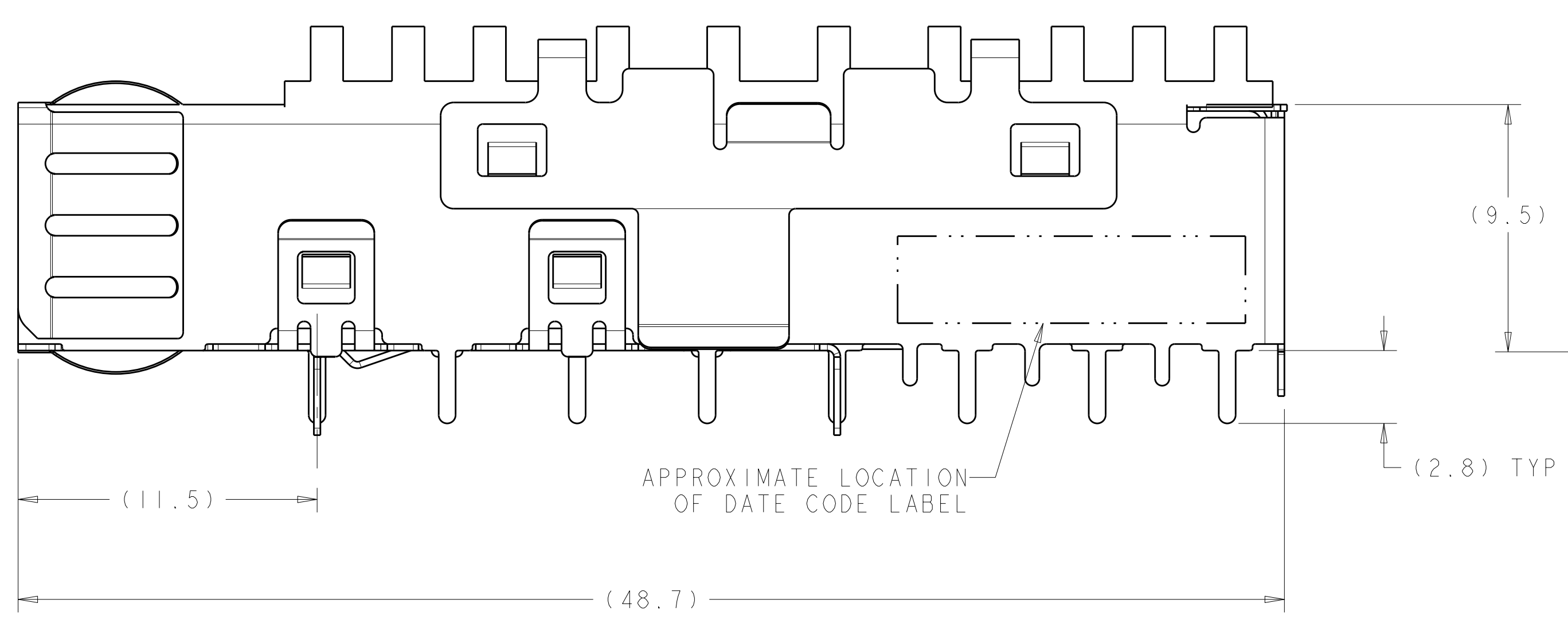
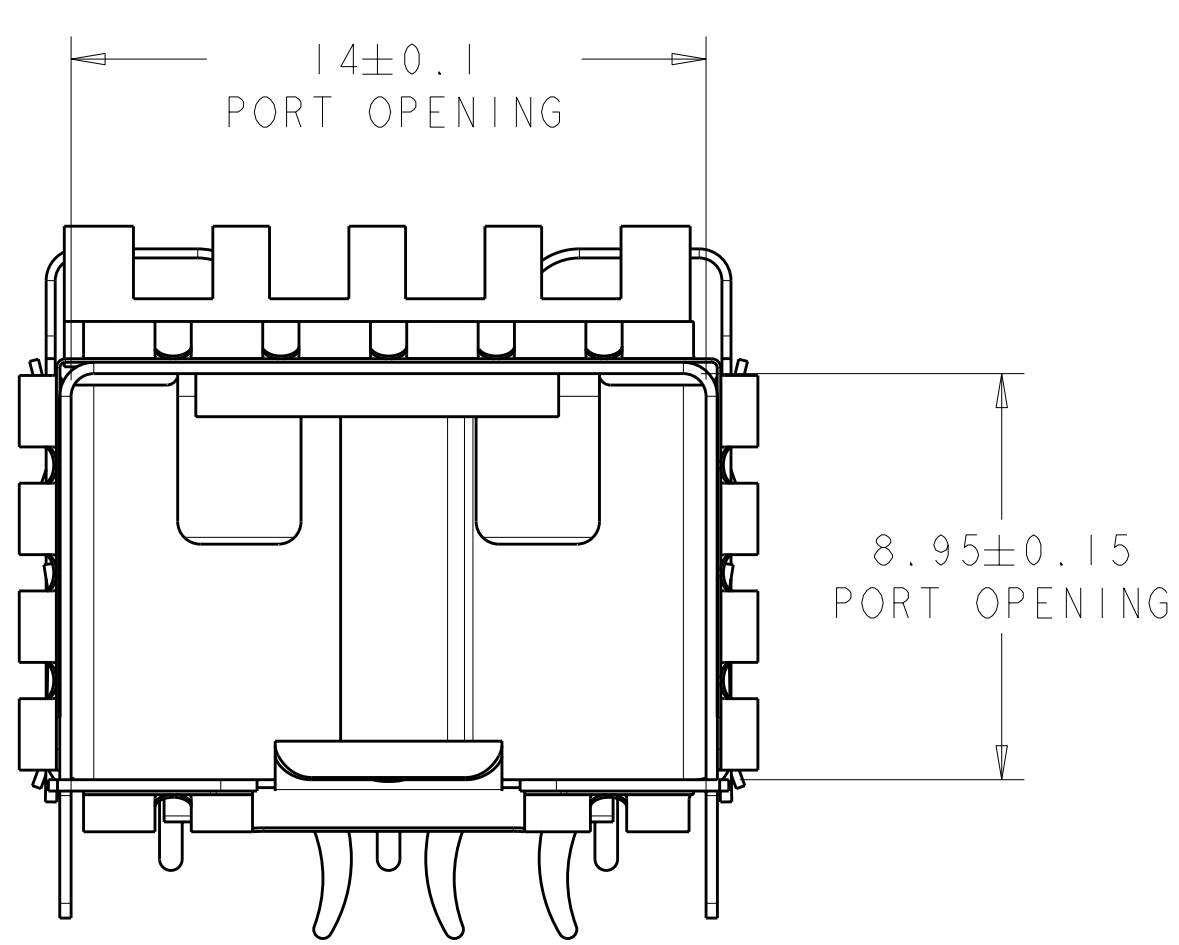


LOC	DIST	REVISIONS			
GP	00	REV	DATE	BY	APPD
		C	200CT2009	CR	MS
		D	26FEB2010	CJV	MRS
		E	05JAN2012	TX	AC

- 1 MATERIAL:
 CAGE ASSEMBLY - NICKEL-SILVER ALLOY.
 EMI SPRINGS - COPPER ALLOY.
 HEATSINK - ALUMINUM ALLOY.
 HEATSINK CLIP - STAINLESS STEEL.
- 2 FINISH:
 HEATSINK - ELECTROLESS NICKEL.
 HEATSINK CLIP - PASSIVATE.
 EMI SPRINGS - 0.8µm MIN MATTE TIN OVER 0.8µm MIN NICKEL.
 NON PLATED EDGES PERMISSIBLE.
- 3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 4 PADS AND VIAS CHASSIS GROUND.
- 5 DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- 6. MINIMUM PC BOARD THICKNESS:
 SINGLE SIDED = 1.50mm
- 7 DIMENSIONS APPLIES PRIOR TO INSERTION OF SFP MODULE.
- 8. CAGE ASSEMBLY, HEATSINK CLIP AND HEATSINK SHIPPED ASSEMBLED.
- 9. NOTE DELETED



2007193-1
 SCALE 5:1

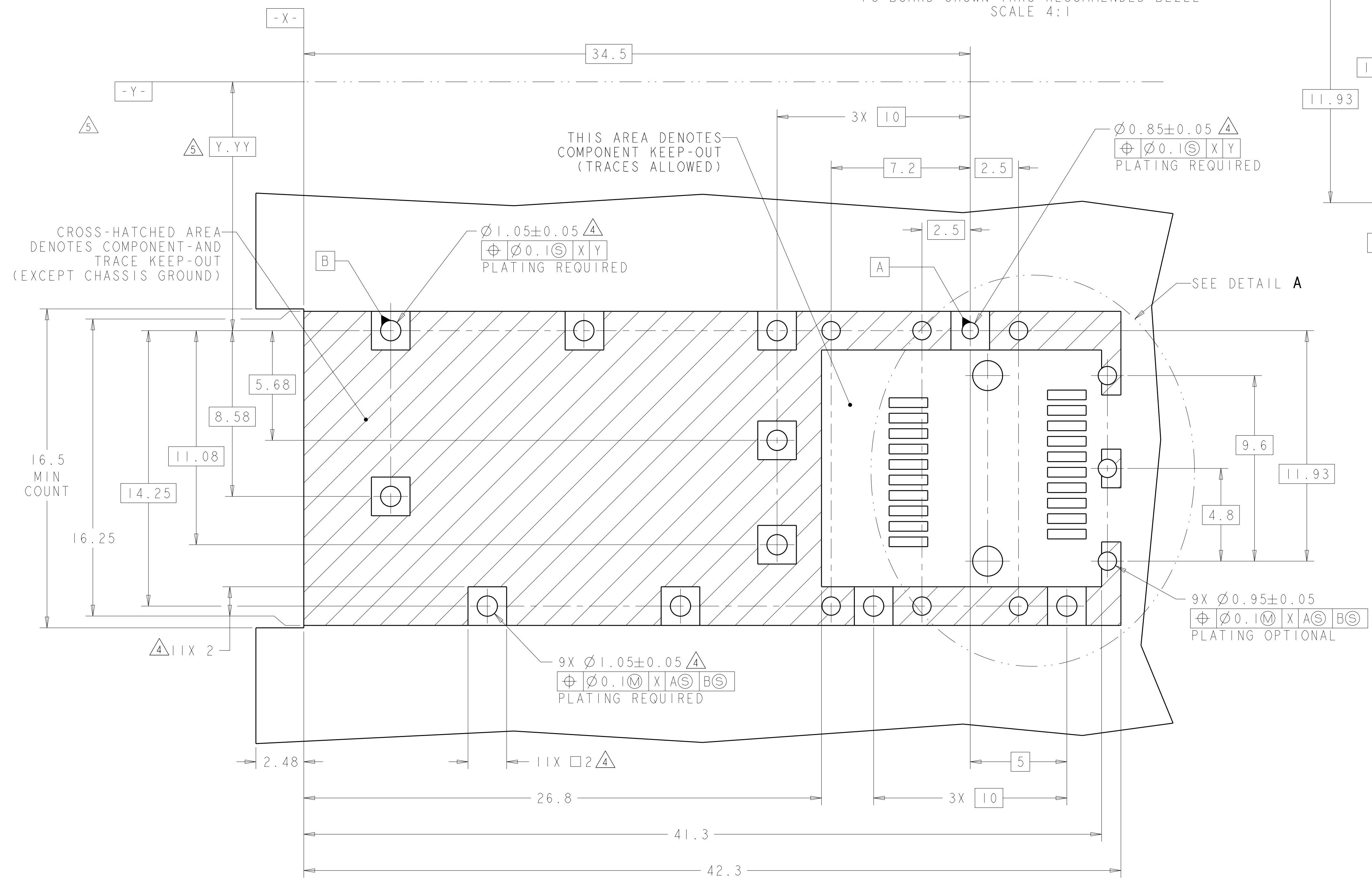
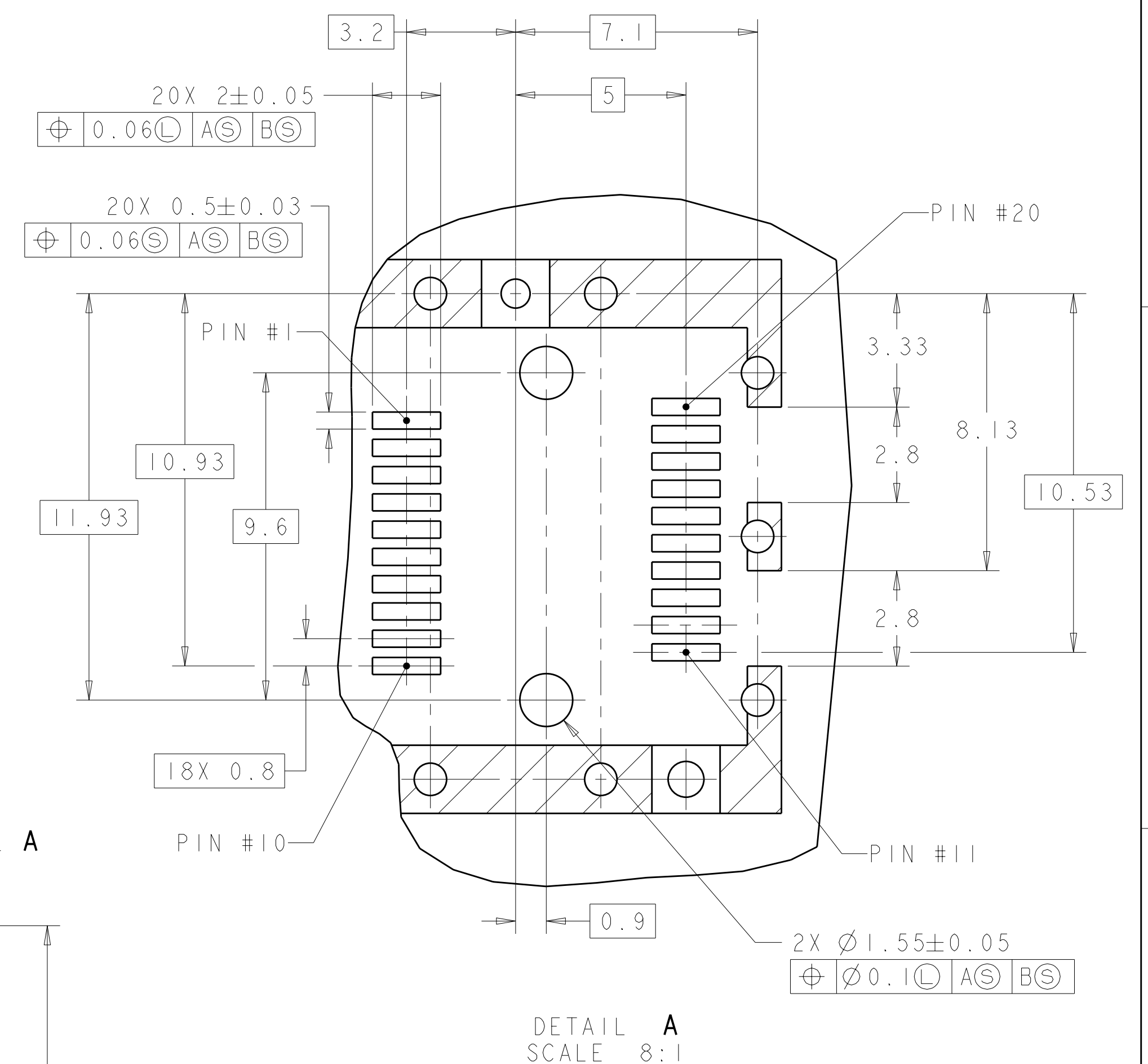
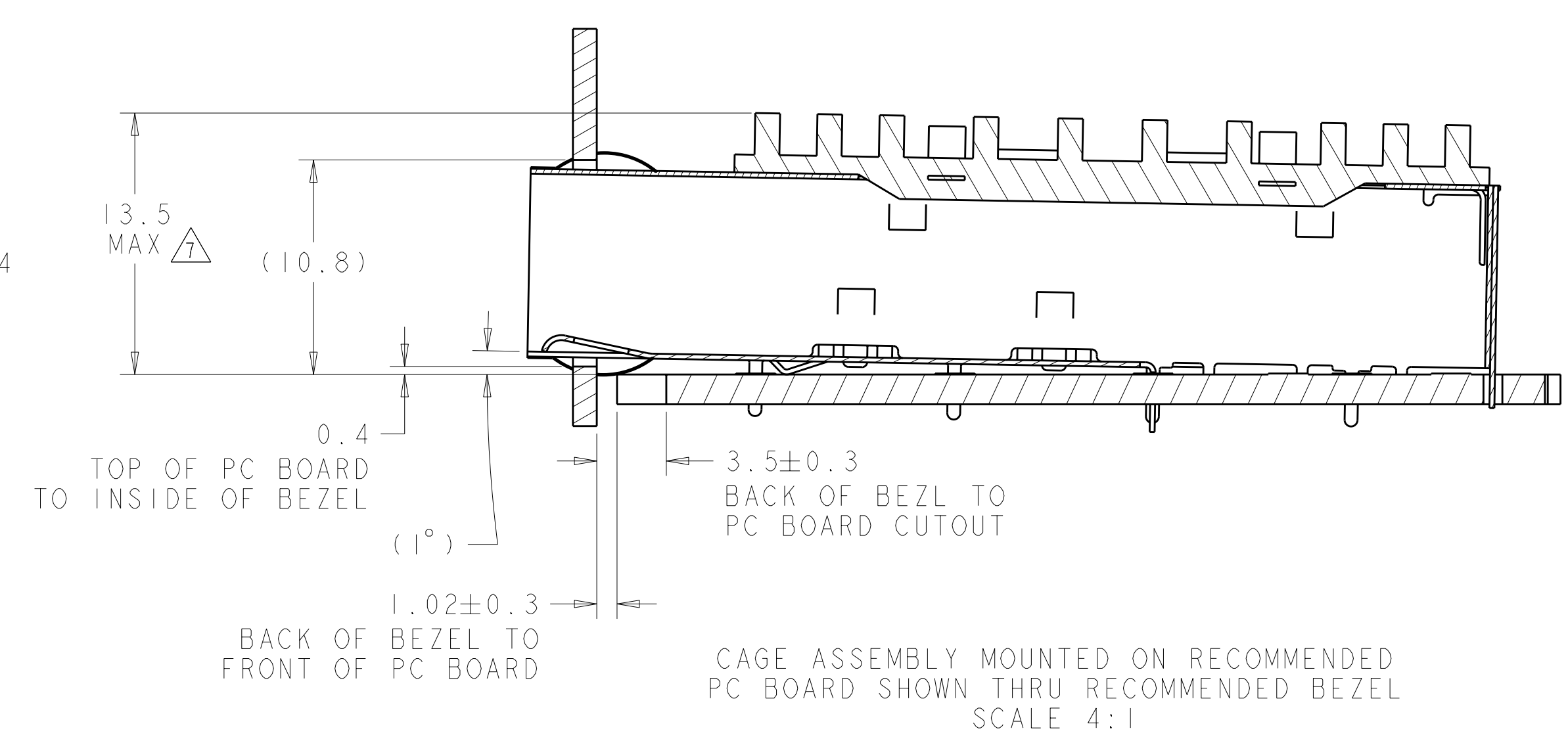
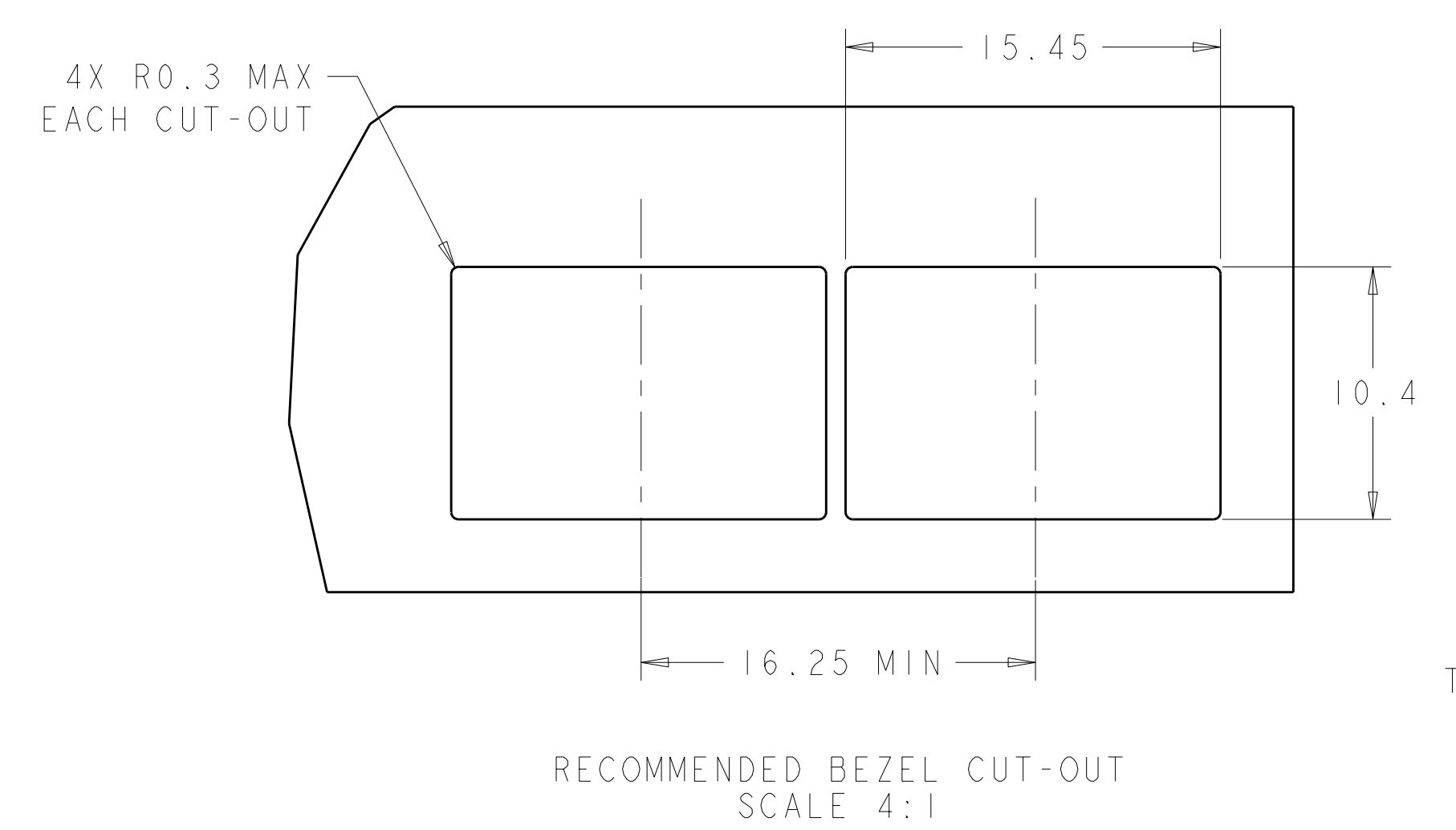


2007193-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN Z. M. BEAM 10JUL2007	TE Connectivity	
DIMENSIONS: mm		CHK M. R. SCHMITT 10JUL2007	NAME SFP+ 1X1 CAGE ASSY W/ HEATSINK PCI SOLDER TAILS EXTERNAL EMI SPRING FINGERS	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ±0.1 5 PLC ±0.1 4 PLC ±0.05 ANGLES ±0.05		APPD P. H. WERTZ 10JUL2007	PRODUCT SPEC 108-2364 APPLICATION SPEC 114-13120	
MATERIAL		WEIGHT	SIZE A100779C=2007193	RESTRICTED TO
FINISH		CUSTOMER DRAWING	SCALE 6:1	SHEET 1 OF 2 REV E

LOC	DIST	REV	DATE	BY	APPD
GP	00				

REVISIONS		DATE	BY	APPD
1	SEE SHEET 1			



RECOMMENDED PCB LAYOUT SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	Z. M. BEAM	10JUL2007
DIMENSIONS:		CHK	M. R. SCHMITT	10JUL2007
mm		APPD	R. H. WERTZ	10JUL2007
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC	NAME	
1 PLC	±0.1	108-2364	SFP+ 1X1 CAGE ASSY W/ HEATSINK	
2 PLC	±0.1	APPLICATION SPEC	PCI SOLDER TAILS	
3 PLC	±0.1	114-13120	EXTERNAL EMI SPRING FINGERS	
4 PLC	±0.05	SIZE	CAGE CODE	DRAWING NO
ANGLES	±0.05	114-13120	A100779	C=2007193
MATERIAL		WEIGHT	RESTRICTED TO	
FINISH		CUSTOMER DRAWING	SCALE	SHEET
			6:1	2 OF 2
				REV E